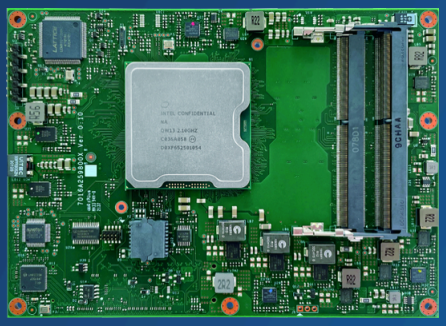
# High-Performance Modular Compute for Demanding Edge Applications

## CME5100

The CME5100 is an extended COM Express Type 7 module designed for high-performance embedded and edge computing. Built around Intel® Xeon® D processing, it provides high memory capacity, up to 32 PCIe Gen3 lanes and high-speed 10GbE KR connectivity, enabling demanding networking, telecom, storage and edge applications.



**CPU**

Intel® Xeon® D processor provides a high-performance foundation for demanding embedded, networking and edge applications

**I/O**

SATA, USB, NCSI, SMBus, UART and SPI interfaces simplify storage, management and peripheral integration

**Form Factor**

Extended COM Express Type 7 architecture combines modular integration with expanded processing and I/O capabilities

**Storage**

eMMC and SPI ROM provide flexible options for system and firmware storage

**Expansion**

Up to 32 PCIe Gen3 lanes support high-speed networking, storage and application-specific expansion

**Security**

TPM 2.0 strengthens the platform security architecture for enterprise and edge deployments

**Memory**

Three DDR4 SO-DIMM sockets provide flexible memory configuration for compute-intensive workloads

**Performance**

Designed for applications requiring more compute and expansion capability than compact entry-level embedded platforms

**Network**

High-speed 10GbE KR connectivity supports advanced network and telecom platforms

**Applications**

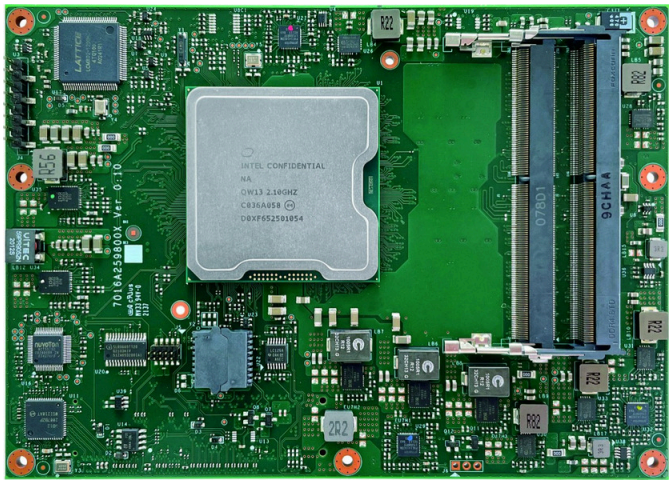
Suitable for network appliances, telecom infrastructure, edge computing and embedded server designs

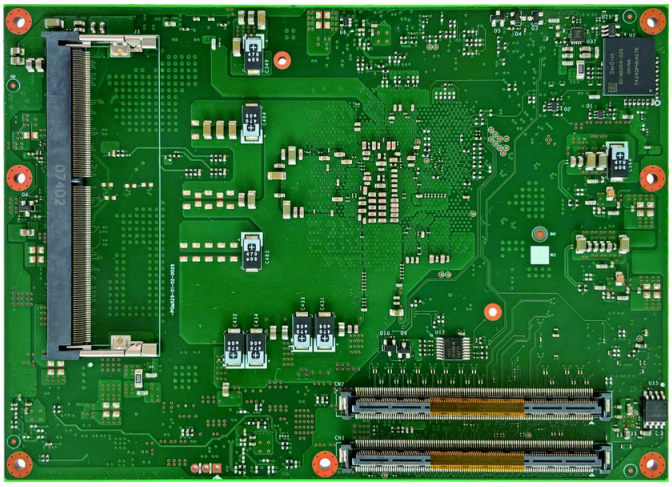
# Technical Specifications

| COM Express Module | |
|---|---|
| Model Name | COM Express Type 7 Module |
| Model Number | CME5100 |
| Processor | Intel® Xeon® Processor<br>Ice Lake-D SoC (up to 10 cores) |
| Memory | 3 x DDR4 SO-DIMM; up to 96 GB ECC |
| Storage | eMMC 5.0 32 GB |
| Network Interfaces | 4 x 10GbE KR |
| I/O / Management | USB 3.0; SATA; NCSI; SMBus; UART |
| Expansion / Architecture | Extended COM Express Type 7; up to 32 PCIe Gen3 lanes |
| Management / Software | Embedded platform management |
| Security | TPM 2.0 |
| Power | Module dependent |
| Cooling | Module / heatsink dependent |
| Environmental | 0–60°C; -40–85°C storage; 5–95% RH, non-condensing |
| Mechanical (W x D x H) | 110 x 155 mm (COM Express Type 7 Extended Size) |
| Compliance | Platform dependent |
| Primary Applications | Network appliances; telecom; edge computing; embedded infrastructure |

# Hardware Overview

CME5100 (COM Express Type 7 Module)





## Senao Networks

Product specifications, configurations, certifications, and availability are subject to change without notice and may vary by region and customer program. Final commitments are governed by the applicable quotation, statement of work, or executed agreement.